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Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are Embedded - System On Chip (SoC)?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions, SoCs combine a central

Details	
Product Status	Obsolete
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	64KB
Peripherals	DMA, POR, WDT
Connectivity	EBI/EMI, Ethernet, I²C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	800MHz
Primary Attributes	FPGA - 462K Logic Elements
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA, FC (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5astfd5g3f35i5n

Advantage	Supporting Feature
Lowest system cost	• Requires as few as four power supplies to operate • Available in thermal composite flip chip ball-grid array (BGA) packaging • Includes innovative features such as Configuration via Protocol (CvP), partial reconfiguration, and design security

Summary of Arria V Features

Table 2: Summary of Features for Arria V Devices

Feature	Description

Technology	• TSMC's 28-nm process technology:
	  • Arria V GX, GT, SX, and ST—28-nm low power (28LP) process
	  • Arria V GZ—28-nm high performance (28HP) process
	• Lowest static power in its class (less than 1.2 W for 500K logic elements (LEs) at 85°C junction under typical conditions)
	• 0.85 V, 1.1 V, or 1.15 V core nominal voltage

Packaging	• Thermal composite flip chip BGA packaging • Multiple device densities with identical package footprints for seamless migration between different device densities • Leaded(1), lead-free (Pb-free), and RoHS-compliant options
High-performance FPGA fabric	• Enhanced 8-input ALM with four registers • Improved routing architecture to reduce congestion and improve compilation time
Internal memory blocks	• M10K—10-kilobits (Kb) memory blocks with soft error correction code (ECC) (Arria V GX, GT, SX, and ST devices only) • M20K—20-Kb memory blocks with hard ECC (Arria V GZ devices only) • Memory logic array block (MLAB)-640-bit distributed LUTRAM where you can use up to 50% of the ALMs as MLAB memory

(1) Contact Altera for availability.

Resource		Member Code							
		A1	A3	A5	A7	B1	B3	B5	B7
6 Gbps Transceiver		9	9	24	24	24	24	36	36
GPIO(3)		416	416	544	544	704	704	704	704
LVDS	Transmitter	67	67	120	120	160	160	160	160
	Receiver	80	80	136	136	176	176	176	176
PCIe Hard IP Block		1	1	2	2	2	2	2	2
Hard Memory Controller		2	2	4	4	4	4	4	4

Related Information

High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook
Provides the number of LVDS channels in each device package.

Package Plan

Table 5: Package Plan for Arria V GX Devices

Member Code	F672 (27 mm)		F896 (31 mm)		F1152 (35 mm)		F1517 (40 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
A1	336	9	416	9	—	—	—	—
A3	336	9	416	9	—	—	—	—
A5	336	9	384	18	544	24	—	—
A7	336	9	384	18	544	24	—	—
B1	—	—	384	18	544	24	704	24
B3	—	—	384	18	544	24	704	24
B5	—	—	—	—	544	24	704	36
B7	—	—	—	—	544	24	704	36

Arria V GT

This section provides the available options, maximum resource counts, and package plan for the Arria V GT devices.

(3) The number of GPIOs does not include transceiver I/Os. In the Quartus® Prime software, the number of user I/Os includes transceiver I/Os.

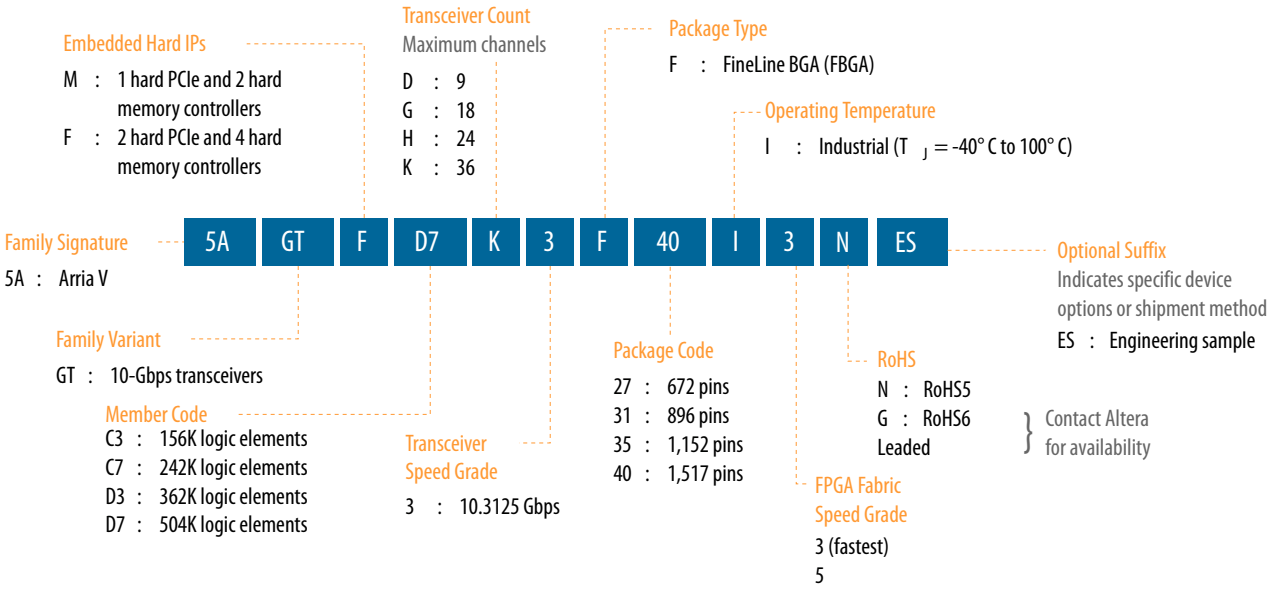
The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Altera Product Selector.

Related Information

Altera Product Selector
Provides the latest information about Altera products.

Available Options

Figure 2: Sample Ordering Code and Available Options for Arria V GT Devices



Maximum Resources

Table 6: Maximum Resource Counts for Arria V GT Devices

Resource		Member Code			
		C3	C7	D3	D7
Logic Elements (LE) (K)		156	242	362	504
ALM		58,900	91,680	136,880	190,240
Register		235,600	366,720	547,520	760,960
Memory (Kb)	M10K	10,510	13,660	17,260	24,140
	MLAB	961	1,448	2,098	2,906
Variable-precision DSP Block		396	800	1,045	1,156
18 x 18 Multiplier		792	1,600	2,090	2,312
PLL		10	12	12	16

Resource		Member Code			
		C3	C7	D3	D7
Transceiver	6 Gbps(4)	3 (9)	6 (24)	6 (24)	6 (36)
	10 Gbps(5)	4	12	12	20
GPIO(6)		416	544	704	704
LVDS	Transmitter	68	120	160	160
	Receiver	80	136	176	176
PCIe Hard IP Block		1	2	2	2
Hard Memory Controller		2	4	4	4

Related Information

- **High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook**
  Provides the number of LVDS channels in each device package.
- **Transceiver Architecture in Arria V Devices**
  Describes 10 Gbps channels usage conditions and SFF-8431 compliance requirements.

Package Plan

Table 7: Package Plan for Arria V GT Devices

Member Code	F672 (27 mm)			F896 (31 mm)			F1152 (35 mm)			F1517 (40 mm)		
	GPIO	XCVR		GPIO	XCVR		GPIO	XCVR		GPIO	XCVR	
		6-Gbps	10-Gbps		6-Gbps	10-Gbps		6-Gbps	10-Gbps		6-Gbps	10-Gbps
C3	336	3 (9)	4	416	3 (9)	4	—	—	—	—	—	—
C7	—	—	—	384	6 (18)	8	544	6 (24)	12	—	—	—
D3	—	—	—	384	6 (18)	8	544	6 (24)	12	704	6 (24)	12
D7	—	—	—	—	—	—	544	6 (24)	12	704	6 (36)	20

The 6-Gbps transceiver counts are for dedicated 6-Gbps channels. You can also configure any pair of 10-Gbps channels as three 6-Gbps channels—the total number of 6-Gbps channels are shown in brackets. For example, you can also configure the Arria V GT D7 device in the F1517 package with nine 6-Gbps

(4) The 6 Gbps transceiver counts are for dedicated 6-Gbps channels. You can also configure any pair of 10 Gbps channels as three 6 Gbps channels-the total number of 6 Gbps channels are shown in brackets.
(5) Chip-to-chip connections only. For 10 Gbps channel usage conditions, refer to the Transceiver Architecture in Arria V Devices chapter.
(6) The number of GPIOs does not include transceiver I/Os. In the Quartus Prime software, the number of user I/Os includes transceiver I/Os.

Resource		Member Code	
		B3	B5
FPGA PLL		14	14
HPS PLL		3	3
6 Gbps Transceiver		30	30
FPGA GPIO[8]		540	540
HPS I/O		208	208
LVDS	Transmitter	120	120
	Receiver	136	136
PCIe Hard IP Block		2	2
FPGA Hard Memory Controller		3	3
HPS Hard Memory Controller		1	1
ARM Cortex-A9 MPCore Processor		Dual-core	Dual-core

Related Information

High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook

Provides the number of LVDS channels in each device package.

Package Plan

Table 11: Package Plan for Arria V SX Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Member Code	F896 (31 mm)			F1152 (35 mm)			F1517 (40 mm)		
	FPGA GPIO	HPS I/O	XCVR	FPGA GPIO	HPS I/O	XCVR	FPGA GPIO	HPS I/O	XCVR
B3	250	208	12	385	208	18	540	208	30
B5	250	208	12	385	208	18	540	208	30

Arria V ST

This section provides the available options, maximum resource counts, and package plan for the Arria V ST devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Altera Product Selector.

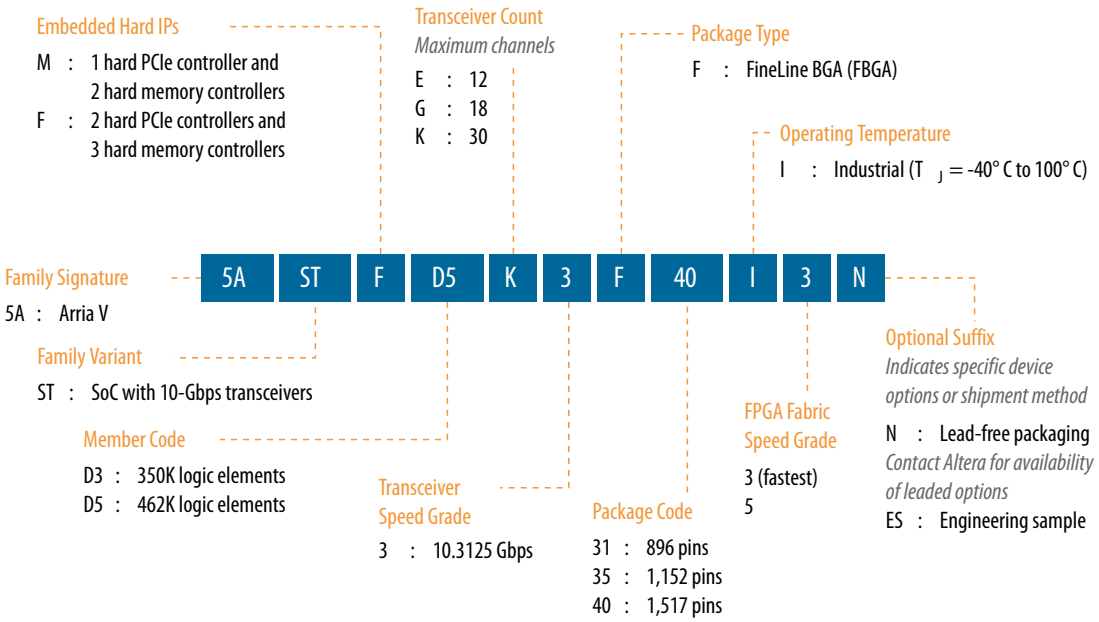
[8] The number of GPIOs does not include transceiver I/Os. In the Quartus Prime software, the number of user I/Os includes transceiver I/Os.

Related Information

Altera Product Selector
Provides the latest information about Altera products.

Available Options

Figure 5: Sample Ordering Code and Available Options for Arria V ST Devices



Maximum Resources

Table 12: Maximum Resource Counts for Arria V ST Devices

Resource		Member Code	
		D3	D5
Logic Elements (LE) (K)		350	462
ALM		132,075	174,340
Register		528,300	697,360
Memory (Kb)	M10K	17,290	22,820
	MLAB	2,014	2,658
Variable-precision DSP Block		809	1,090
18 x 18 Multiplier		1,618	2,180
FPGA PLL		14	14
HPS PLL		3	3
Transceiver	6-Gbps	30	30
	10-Gbps[9]	16	16

Resource		Member Code	
		D3	D5
FPGA GPIO(10)		540	540
HPS I/O		208	208
LVDS	Transmitter	120	120
	Receiver	136	136
PCIe Hard IP Block		2	2
FPGA Hard Memory Controller		3	3
HPS Hard Memory Controller		1	1
ARM Cortex-A9 MPCore Processor		Dual-core	Dual-core

Related Information

- **High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook**
  Provides the number of LVDS channels in each device package.
- **Transceiver Architecture in Arria V Devices**
  Describes 10 Gbps channels usage conditions and SFF-8431 compliance requirements.

Package Plan

Table 13: Package Plan for Arria V ST Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Member Code	F896 (31 mm)				F1152 (35 mm)				F1517 (40 mm)			
	FPGA GPIO	HPS I/O	XCVR		FPGA GPIO	HPS I/O	XCVR		FPGA GPIO	HPS I/O	XCVR	
			6 Gbps	10 Gbps			6 Gbps	10 Gbps			6 Gbps	10 Gbps
D3	250	208	12	6	385	208	18	8	540	208	30	16
D5	250	208	12	6	385	208	18	8	540	208	30	16

(9) Chip-to-chip connections only. For 10 Gbps channel usage conditions, refer to the Transceiver Architecture in Arria V Devices chapter.

(10) The number of GPIOs does not include transceiver I/Os. In the Quartus Prime software, the number of user I/Os includes transceiver I/Os.

Variable-Precision DSP Block

Arria V devices feature a variable-precision DSP block that supports these features:

- Configurable to support signal processing precisions ranging from 9 x 9, 18 x 18, 27 x 27, and 36 x 36 bits natively
- A 64-bit accumulator
- Double accumulator
- A hard preadder that is available in both 18- and 27-bit modes
- Cascaded output adders for efficient systolic finite impulse response (FIR) filters
- Dynamic coefficients
- 18-bit internal coefficient register banks
- Enhanced independent multiplier operation
- Efficient support for single-precision floating point arithmetic
- The inferability of all modes by the Quartus Prime design software

Table 14: Variable-Precision DSP Block Configurations for Arria V Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resource
Low precision fixed point for video applications	Three 9 x 9	1
Medium precision fixed point in FIR filters	Two 18 x 18	1
FIR filters	Two 18 x 18 with accumulate	1
Single-precision floating-point implementations	One 27 x 27	1
Very high precision fixed point implementations	One 36 x 36	2

You can configure each DSP block during compilation as independent three 9 x 9, two 18 x 18, or one 27 x 27 multipliers. Using two DSP block resources, you can also configure a 36 x 36 multiplier for high-precision applications. With a dedicated 64 bit cascade bus, you can cascade multiple variable-precision DSP blocks to implement even higher precision DSP functions efficiently.

Table 15: Number of Multipliers in Arria V Devices

The table lists the variable-precision DSP resources by bit precision for each Arria V device.

Variant	Member Code	Variable-precision DSP Block	Independent Input and Output Multiplications Operator				18 x 18 Multiplier Adder Mode	18 x 18 Multiplier Adder Summed with 36 bit Input
			9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier	36 x 36 Multiplier		
Arria V GX	A1	240	720	480	240	—	240	240
	A3	396	1,188	792	396	—	396	396
	A5	600	1,800	1,200	600	—	600	600
	A7	800	2,400	1,600	800	—	800	800
	B1	920	2,760	1,840	920	—	920	920
	B3	1,045	3,135	2,090	1,045	—	1,045	1,045
	B5	1,092	3,276	2,184	1,092	—	1,092	1,092
	B7	1,156	3,468	2,312	1,156	—	1,156	1,156
Arria V GT	C3	396	1,188	792	396	—	396	396
	C7	800	2,400	1,600	800	—	800	800
	D3	1,045	3,135	2,090	1,045	—	1,045	1,045
	D7	1,156	3,468	2,312	1,156	—	1,156	1,156
Arria V GZ	E1	800	2,400	1,600	800	400	800	800
	E3	1,044	3,132	2,088	1,044	522	1,044	1,044
	E5	1,092	3,276	2,184	1,092	546	1,092	1,092
	E7	1,139	3,417	2,278	1,139	569	1,139	1,139
Arria V SX	B3	809	2,427	1,618	809	—	809	809
	B5	1,090	3,270	2,180	1,090	—	1,090	1,090
Arria V ST	D3	809	2,427	1,618	809	—	809	809
	D5	1,090	3,270	2,180	1,090	—	1,090	1,090

Embedded Memory Blocks

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.

Variant	Member Code	M20K		M10K		MLAB		Total RAM Bit (Kb)
		Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	
Arria V ST	D3	—	—	1,729	17,290	3223	2,014	19,304
	D5	—	—	2,282	22,820	4253	2,658	25,478

Embedded Memory Configurations

Table 17: Supported Embedded Memory Block Configurations for Arria V Devices

This table lists the maximum configurations supported for the embedded memory blocks. The information is applicable only to the single-port RAM and ROM modes.

Memory Block	Depth (bits)	Programmable Width
MLAB	32	x16, x18, or x20
	64(11)	x10
M20K	512	x40
	1K	x20
	2K	x10
	4K	x5
	8K	x2
	16K	x1
M10K	256	x40 or x32
	512	x20 or x16
	1K	x10 or x8
	2K	x5 or x4
	4K	x2
	8K	x1

Clock Networks and PLL Clock Sources

650 MHz Arria V devices have 16 global clock networks capable of up to operation. The clock network architecture is based on Altera's global, quadrant, and peripheral clock structure. This clock structure is supported by dedicated clock input pins and fractional PLLs.

Note: To reduce power consumption, the Quartus Prime software identifies all unused sections of the clock network and powers them down.

(11) Available for Arria V GZ devices only.

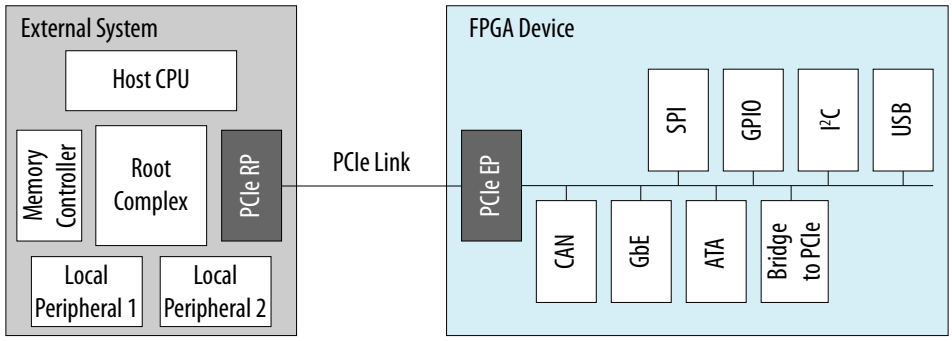
PCIe Gen1, Gen2, and Gen 3 Hard IP

Arria V devices contain PCIe hard IP that is designed for performance and ease-of-use. The PCIe hard IP consists of the MAC, data link, and transaction layers.

The PCIe hard IP supports PCIe Gen3, Gen 2, and Gen 1 end point and root port for up to x8 lane configuration.

The PCIe endpoint support includes multifunction support for up to eight functions, as shown in the following figure. The integrated multifunction support reduces the FPGA logic requirements by up to 20,000 LEs for PCIe designs that require multiple peripherals.

Figure 8: PCIe Multifunction for Arria V Devices



The Arria V PCIe hard IP operates independently from the core logic. This independent operation allows the PCIe link to wake up and complete link training in less than 100 ms while the Arria V device completes loading the programming file for the rest of the device.

In addition, the PCIe hard IP in the Arria V device provides improved end-to-end datapath protection using ECC.

External Memory Interface

This section provides an overview of the external memory interface in Arria V devices.

Hard and Soft Memory Controllers

Arria V GX,GT, SX, and ST devices support up to four hard memory controllers for DDR3 and DDR2 SDRAM devices. Each controller supports 8 to 32 bit components of up to 4 gigabits (Gb) in density with two chip selects and optional ECC. For the Arria V SoC devices, an additional hard memory controller in the HPS supports DDR3, DDR2, and LPDDR2 SDRAM devices.

All Arria V devices support soft memory controllers for DDR3, DDR2, and LPDDR2 SDRAM devices, QDR II+, QDR II, and DDR II+ SRAM devices, and RLDRAM II devices for maximum flexibility.

Note: DDR3 SDRAM leveling is supported only in Arria V GZ devices.

External Memory Performance

Table 18: External Memory Interface Performance in Arria V Devices

Interface	Voltage (V)	Hard Controller (MHz)	Soft Controller (MHz)	
		Arria V GX, GT, SX, and ST	Arria V GX, GT, SX, and ST	Arria V GZ
DDR3 SDRAM	1.5	533	667	800
	1.35	533	600	800
DDR2 SDRAM	1.8	400	400	400
LPDDR2 SDRAM	1.2	—	400	—
RLDRAM 3	1.2	—	—	667
RLDRAM II	1.8	—	400	533
	1.5	—	400	533
QDR II+ SRAM	1.8	—	400	500
	1.5	—	400	500
QDR II SRAM	1.8	—	400	333
	1.5	—	400	333
DDR II+ SRAM(12)	1.8	—	400	—
	1.5	—	400	—

Related Information

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Altera's External Memory Interface Spec Estimator tool.

HPS External Memory Performance

Table 19: HPS External Memory Interface Performance

The hard processor system (HPS) is available in Arria V SoC devices only.

Interface	Voltage (V)	HPS Hard Controller (MHz)
DDR3 SDRAM	1.5	533
	1.35	533
LPDDR2 SDRAM	1.2	333

(12) Not available as Altera® IP.

Figure 10: Device Chip Overview for Arria V GZ Devices

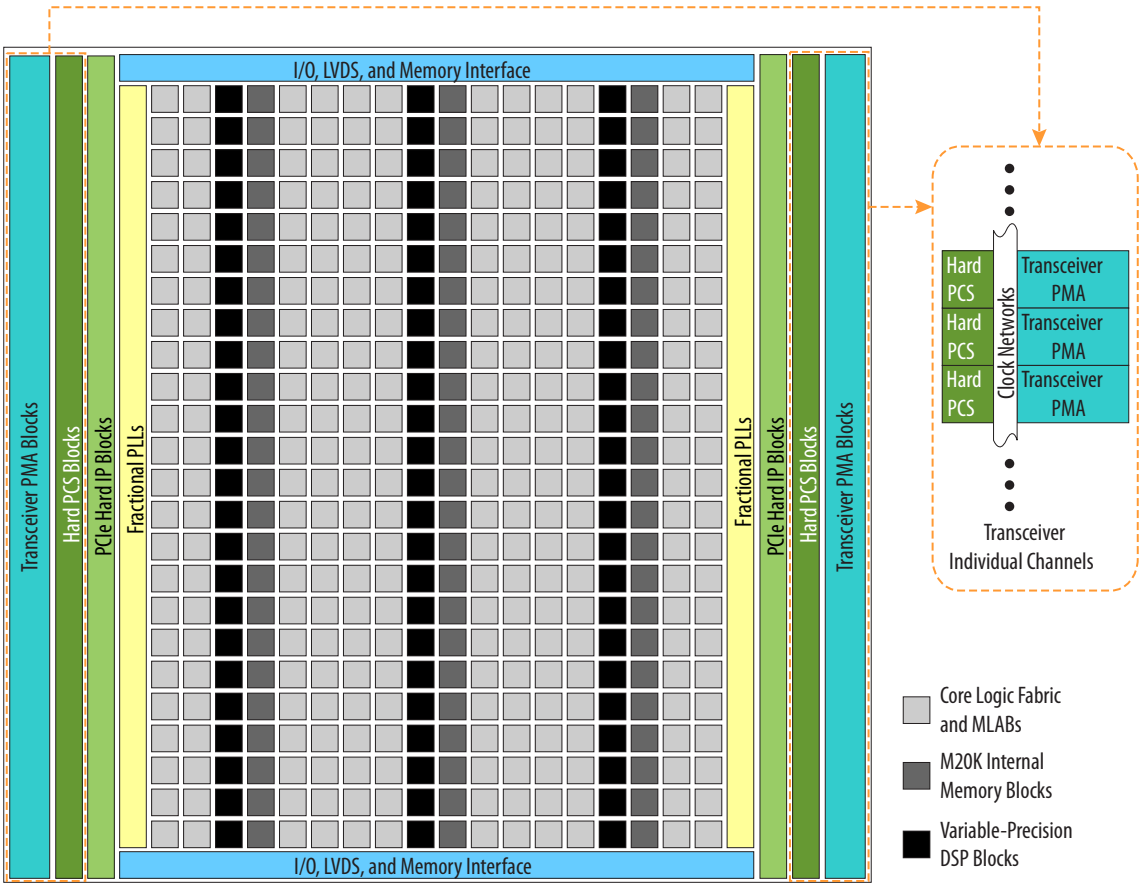
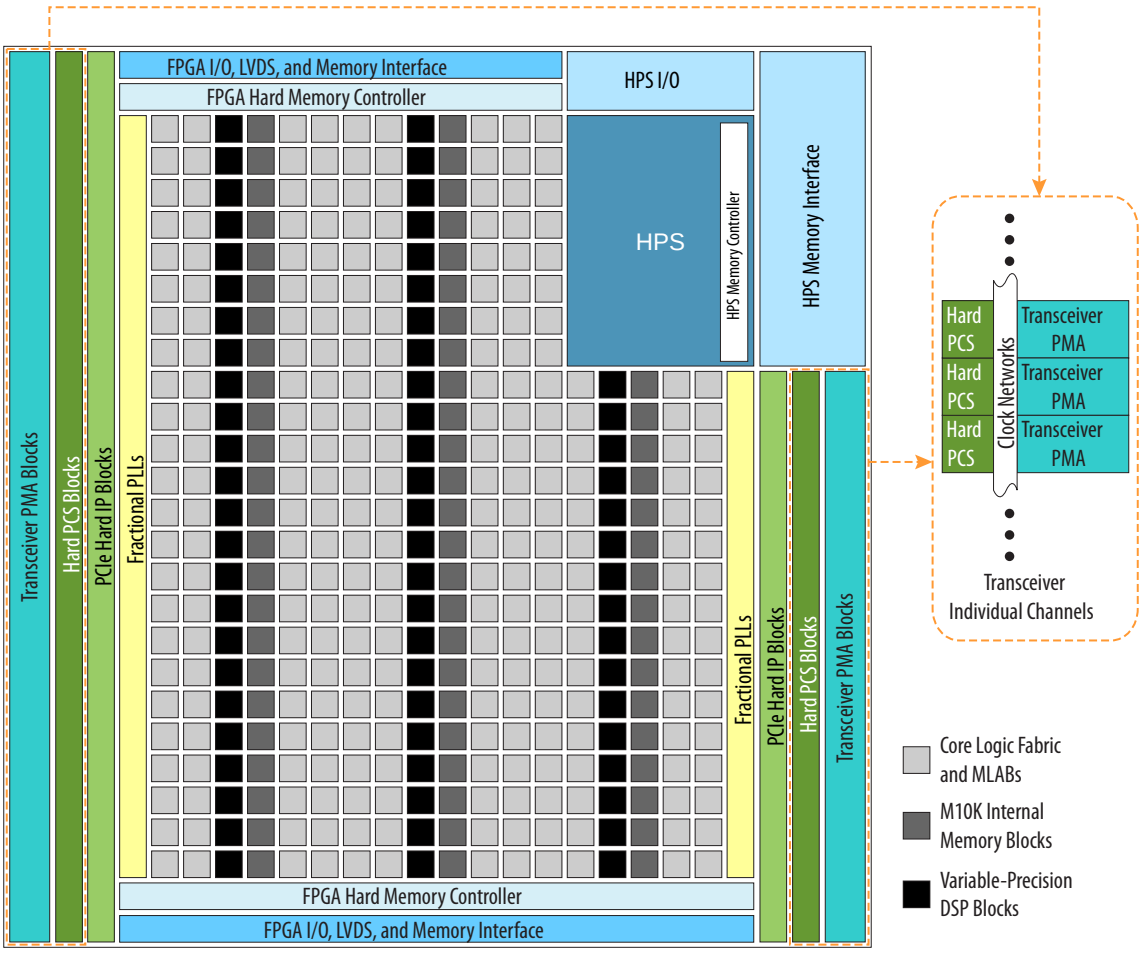


Figure 11: Device Chip Overview for Arria V SX and ST Devices



PMA Features

To prevent core and I/O noise from coupling into the transceivers, the PMA block is isolated from the rest of the chip—ensuring optimal signal integrity. For the transceivers, you can use the channel PLL of an unused receiver PMA as an additional transmit PLL.

Table 20: PMA Features of the Transceivers in Arria V Devices

Features	Capability
Backplane support	• Arria V GX, GT, SX, and ST devices—Driving capability at 6.5536 Gbps with up to 25 dB channel loss • Arria V GZ devices—Driving capability at 12.5 Gbps with up to 16 dB channel loss
Chip-to-chip support	• Arria V GX, GT, SX, and ST devices—Up to 10.3125 Gbps • Arria V GZ devices—Up to 12.5 Gbps

Features	Capability
PLL-based clock recovery	Superior jitter tolerance
Programmable serializer and deserializer (SERDES)	Flexible SERDES width
Equalization and pre-emphasis	• Arria V GX, GT, SX, and ST devices—Up to 14.37 dB of pre-emphasis and up to 4.7 dB of equalization • Arria V GZ devices—4-tap pre-emphasis and de-emphasis
Ring oscillator transmit PLLs	611 Mbps to 10.3125 Gbps
LC oscillator ATX transmit PLLs (Arria V GZ devices only)	600 Mbps to 12.5 Gbps
Input reference clock range	27 MHz to 710 MHz
Transceiver dynamic reconfiguration	Allows the reconfiguration of a single channel without affecting the operation of other channels

PCS Features

The Arria V core logic connects to the PCS through an 8, 10, 16, 20, 32, 40, 64, 66, or 67 bit interface, depending on the transceiver data rate and protocol. Arria V devices contain PCS hard IP to support PCIe Gen1, Gen2, and Gen3, GbE, Serial RapidIO (SRIO), GPON, and CPRI.

All other standard and proprietary protocols within the following speed ranges are also supported:

- 611 Mbps to 6.5536 Gbps—supported through the custom double-width mode (up to 6.5536 Gbps) and custom single-width mode (up to 3.75 Gbps) of the transceiver PCS hard IP.
- 6.5536 Gbps to 10.3125 Gbps—supported through dedicated 80 or 64 bit interface that bypass the PCS hard IP and connects the PMA directly to the core logic. In Arria V GZ, this is supported in the transceiver PCS hard IP.

Table 21: Transceiver PCS Features for Arria V GX, GT, ST, and SX Devices

PCS Support[13]	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
Custom single- and double-width modes	0.611 to ~6.5536	• Phase compensation FIFO • Byte serializer • 8B/10B encoder	• Word aligner • 8B/10B decoder • Byte deserializer • Phase compensation FIFO
SRIO	1.25 to 6.25		
Serial ATA	1.5, 3.0, 6.0		

[13] Data rates above 6.5536 Gbps up to 10.3125 Gbps, such as 10GBASE-R, are supported through the soft PCS.

PCS Support[13]	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
PCIe Gen1 (x1, x2, x4, x8)	2.5 and 5.0	• Phase compensation FIFO • Byte serializer • 8B/10B encoder • PIPE 2.0 interface to the core logic	• Word aligner • 8B/10B decoder • Byte deserializer • Phase compensation FIFO • Rate match FIFO • PIPE 2.0 interface to the core logic
PCIe Gen2[14] (x1, x2, x4)			
GbE	1.25	• Phase compensation FIFO • Byte serializer • 8B/10B encoder	• Word aligner • 8B/10B decoder • Byte deserializer • Phase compensation FIFO • Rate match FIFO
XAUI[15]	3.125	• Phase compensation FIFO • Byte serializer • 8B/10B encoder • XAUI state machine for bonding four channels	• Word aligner • 8B/10B decoder • Byte deserializer • Phase compensation FIFO • XAUI state machine for realigning four channels • Deskew FIFO circuitry
SDI	0.27[16], 1.485, 2.97	• Phase compensation FIFO • Byte serializer	• Byte deserializer • Phase compensation FIFO
GPON[17]	1.25 and 2.5		
CPRI[18]	0.6144 to 6.144	• Phase compensation FIFO • Byte serializer • 8B/10B encoder • TX deterministic latency	• Word aligner • 8B/10B decoder • Byte deserializer • Phase compensation FIFO • RX deterministic latency

(13) Data rates above 6.5536 Gbps up to 10.3125 Gbps, such as 10GBASE-R, are supported through the soft PCS.
(14) PCIe Gen2 is supported only through the PCIe hard IP.
(15) XAUI is supported through the soft PCS.
(16) The 0.27 Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.
(17) The GPON standard does not support burst mode.
(18) CPRI data rates above 6.5536 Gbps, such as 9.8304 Gbps, are supported through the soft PCS.

Protocol	Data Rates (Gbps)	Transmitter Data Path Features	Receiver Data Path Features
40GBASE-R Ethernet	4 x 10.3125	• TX FIFO • 64B/66B encoder • Scrambler • Alignment marker insertion • Gearbox • Block stripper	• RX FIFO • 64B/66B decoder • Descrambler • Lane reorder • Deskew • Alignment marker lock • Block synchronization • Gear box • Destripper
100GBASE-R Ethernet	10 x 10.3125		
40G and 100G OTN	(4 +1) x 11.3 (10 +1) x 11.3	• TX FIFO • Channel bonding • Byte serializer	• RX FIFO • Lane deskew • Byte deserializer
GbE	1.25	• Phase compensation FIFO • Byte serializer • 8B/10B encoder • Bit-slip • Channel bonding • GbE state machine	• Word aligner • Deskew FIFO • Rate match FIFO • 8B/10B decoder • Byte deserializer • Byte ordering • GbE state machine
XAUI	3.125 to 4.25	• Phase compensation FIFO • Byte serializer • 8B/10B encoder • Bit-slip • Channel bonding • XAUI state machine for bonding four channels	• Word aligner • Deskew FIFO • Rate match FIFO • 8B/10B decoder • Byte deserializer • Byte ordering • XAUI state machine for realigning four channels
SRIO	1.25 to 6.25	• Phase compensation FIFO • Byte serializer • 8B/10B encoder • Bit-slip • Channel bonding • SRIO V2.1-compliant x2 and x4 channel bonding	• Word aligner • Deskew FIFO • Rate match FIFO • 8B/10B decoder • Byte deserializer • Byte ordering • SRIO V2.1-compliant x2 and x4 deskew state machine

SoC with HPS

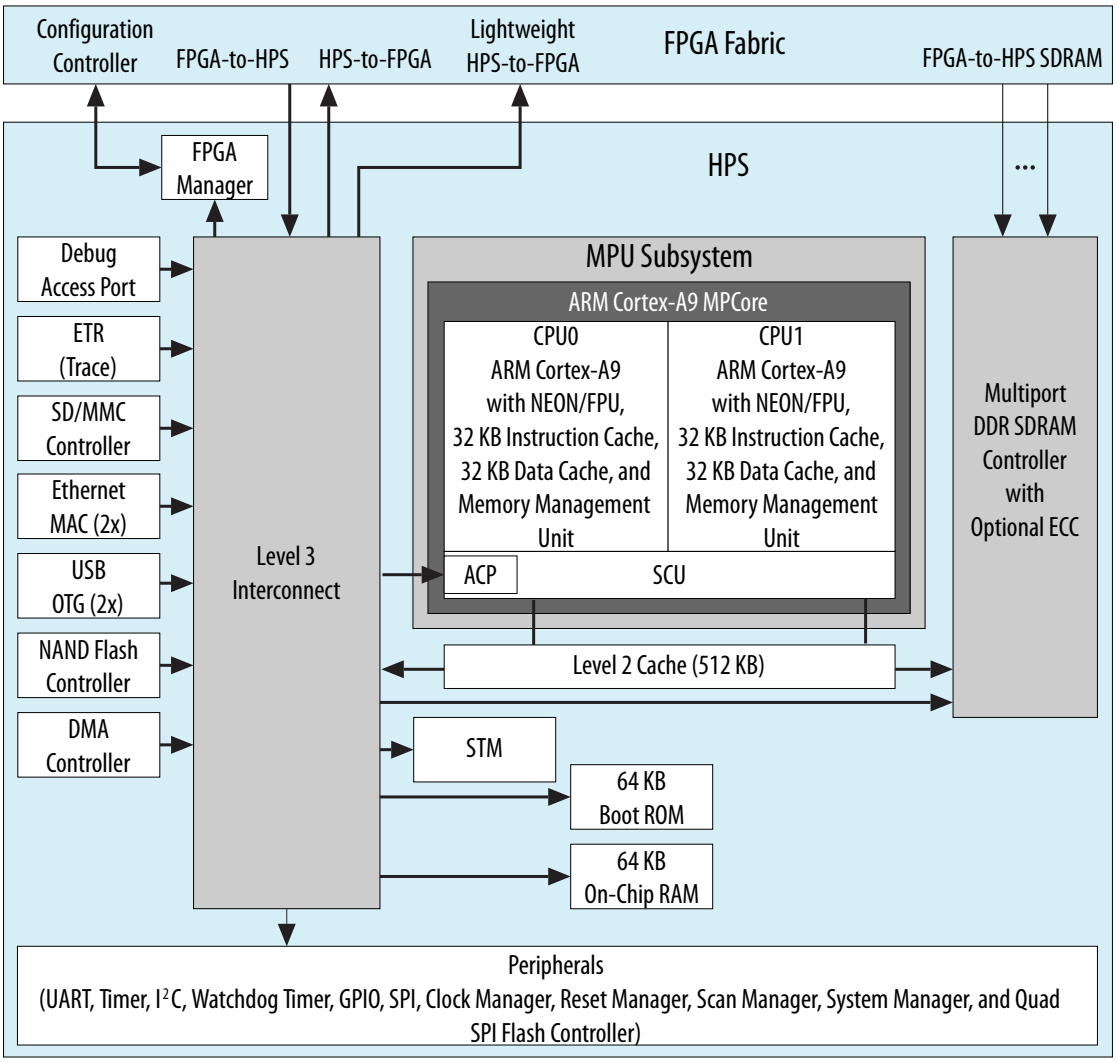
Each SoC combines an FPGA fabric and an HPS in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

HPS Features

The HPS consists of a dual-core ARM Cortex-A9 MPCore processor, a rich set of peripherals, and a shared multiport SDRAM memory controller, as shown in the following figure.

Figure 12: HPS with Dual-Core ARM Cortex-A9 MPCore Processor



System Peripherals and Debug Access Port

Each Ethernet MAC, USB OTG, NAND flash controller, and SD/MMC controller module has an integrated DMA controller. For modules without an integrated DMA controller, an additional DMA controller module provides up to eight channels of high-bandwidth data transfers. Peripherals that communicate off-chip are multiplexed with other peripherals at the HPS pin level. This allows you to choose which peripherals to interface with other devices on your PCB.

The debug access port provides interfaces to industry standard JTAG debug probes and supports ARM CoreSight debug and core traces to facilitate software development.

HPS–FPGA AXI Bridges

The HPS–FPGA bridges, which support the Advanced Microcontroller Bus Architecture (AMBA®) Advanced eXtensible Interface (AXI™) specifications, consist of the following bridges:

- FPGA-to-HPS AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the FPGA fabric to issue transactions to slaves in the HPS.
- HPS-to-FPGA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the HPS to issue transactions to slaves in the FPGA fabric.
- Lightweight HPS-to-FPGA AXI bridge—a lower latency 32 bit width bus that allows the HPS to issue transactions to slaves in the FPGA fabric. This bridge is primarily used for control and status register (CSR) accesses to peripherals in the FPGA fabric.

The HPS–FPGA AXI bridges allow masters in the FPGA fabric to communicate with slaves in the HPS logic, and vice versa. For example, the HPS-to-FPGA AXI bridge allows you to share memories instantiated in the FPGA fabric with one or both microprocessors in the HPS, while the FPGA-to-HPS AXI bridge allows logic in the FPGA fabric to access the memory and peripherals in the HPS.

Each HPS–FPGA bridge also provides asynchronous clock crossing for data transferred between the FPGA fabric and the HPS.

HPS SDRAM Controller Subsystem

The HPS SDRAM controller subsystem contains a multiport SDRAM controller and DDR PHY that are shared between the FPGA fabric (through the FPGA-to-HPS SDRAM interface), the level 2 (L2) cache, and the level 3 (L3) system interconnect. The FPGA-to-HPS SDRAM interface supports AMBA AXI and Avalon® Memory-Mapped (Avalon-MM) interface standards, and provides up to six individual ports for access by masters implemented in the FPGA fabric.

To maximize memory performance, the SDRAM controller subsystem supports command and data reordering, deficit round-robin arbitration with aging, and high-priority bypass features. The SDRAM controller subsystem supports DDR2, DDR3, or LPDDR2 devices up to 4 Gb in density operating at up to 533 MHz (1066 Mbps data rate).

FPGA Configuration and Processor Booting

The FPGA fabric and HPS in the SoC are powered independently. You can reduce the clock frequencies or gate the clocks to reduce dynamic power, or shut down the entire FPGA fabric to reduce total system power.

Date	Version	Changes
July 2012	2.1	• Added –I3 speed grade to Figure 1 for Arria V GX devices. • Updated the 6-Gbps transceiver speed from 6.553 Gbps to 6.5536 Gbps in Figure 3 and Figure 1.
June 2012	2.0	• Restructured the document. • Added the "Embedded Memory Capacity" and "Embedded Memory Configurations" sections. • Added Table 1, Table 3, Table 12, Table 15, and Table 16. • Updated Table 2, Table 4, Table 5, Table 6, Table 7, Table 8, Table 9, Table 10, Table 11, Table 13, Table 14, and Table 19. • Updated Figure 1, Figure 2, Figure 3, Figure 4, and Figure 8. • Updated the "FPGA Configuration and Processor Booting" and "Hardware and Software Development" sections. • Text edits throughout the document.
February 2012	1.3	• Updated Table 1–7 and Table 1–8. • Updated Figure 1–9 and Figure 1–10. • Minor text edits.
December 2011	1.2	Minor text edits.
November 2011	1.1	• Updated Table 1–1, Table 1–2, Table 1–3, Table 1–4, Table 1–6, Table 1–7, Table 1–9, and Table 1–10. • Added "SoC FPGA with HPS" section. • Updated "Clock Networks and PLL Clock Sources" and "Ordering Information" sections. • Updated Figure 1–5. • Added Figure 1–6. • Minor text edits.
August 2011	1.0	Initial release.